

Serial No.: 09/627,979
Art Unit: 2814

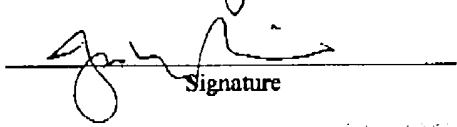
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: **09/627,979** Examiner: **DiLinh Nguyen**
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Filed: **June 24, 2000** Art Unit: **2814**
Title: **Method Of Packaging Multi Chip Module**

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Signature

Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT C

In response to the Office Action mailed 11/20/2002, please amend the above-identified application as follows:

SPECIFICATION:

Page 6, between lines 6 and 7, insert the following paragraph:

The present invention presents an MCM package structure in which at least one CSP is packaged along with another CSP or a bare die. In other words, there are two levels of packaged structures in the MCM package. The conventional CSP forms the first level of the packaged structure and the MCM forms the second level of the packaged structure. As shown in FIG. 2A, a conventional CSP 221 has a bare die 22 embedded and disposed above a CSP substrate 21, wires 25 for connecting the bare die 22 to the